

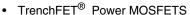


N-Channel 150-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
150	0.050 at V _{GS} = 10 V	6.7		

FEATURES

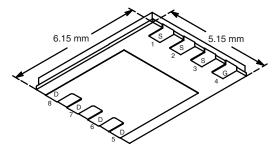
 Halogen-free According to IEC 61249-2-21 Definition



- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07 mm Profile
- PWM Optimized for Fast Switching
- 100 % R_q Tested

ROHS COMPLIANT HALOGEN FREE





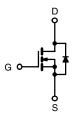
Bottom View

Ordering Information: Si7846DP-T1-E3 (Lead (Pb)-free)

Si7846DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

APPLICATIONS

- Primary Side Switch for High Density DC/DC
- Telecom/Server 48 V DC/DC
- Industrial and 42 V Automotive



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$T_A = 25 ^{\circ}C$, unles	ss otherwise r	noted			
Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V_{DS}	150		٧	
Gate-Source Voltage		V_{GS}	± 20			
	T _C = 25 °C		24.5			
Continuous Drain Current (T _{.I} = 150 °C) ^a	T _C = 70 °C	I _D	19.5			
Continuous Diain Current (1 j = 150°C)	T _A = 25 °C		6.7	4.0		
	T _A = 70 °C		5.4	3.3	Α	
Pulsed Drain Current		I _{DM}	50			
Avalanche Current	L = 0.1 mH	I _{AS}	25			
Continuous Source Current (Diode Conduction) ^a	I _S	4.3	1.6			
Maximum Dawar Dissination	T _A = 25 °C	P _D	5.2	1.9	W	
Maximum Power Dissipation ^a	T _A = 70 °C		3.3	1.2		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C	
Soldering Recommendations (Peak Temperature)b, c			260		<u> </u>	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian II matica to Ambienta	t ≤ 10 s	R _{thJA}	19	24	°C/W
Maximum Junction-to-Ambient ^a	Steady State		52	65	
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	1.5	1.8	

Notes

- a. Surface Mounted on 1" x 1" FR4 board.
- b. See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

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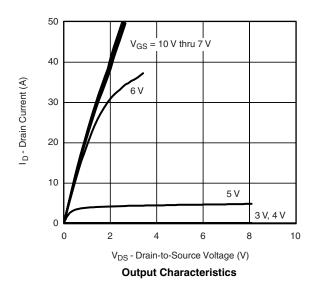
SPECIFICATIONS $T_J = 25$ °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Cata Valtana Duain Commant		V _{DS} = 150 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	IDSS	V_{DS} = 150 V, V_{GS} = 0 V, T_{J} = 55 °C			5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 5 A		0.041	0.050	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 5 A		18		S	
Diode Forward Voltage ^a	V_{SD}	I _S = 2.8 A, V _{GS} = 0 V		0.75	1.1	V	
Dynamic ^b							
Total Gate Charge	Q_g			30	36	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		8.5			
Gate-Drain Charge	Q_{gd}			8.5			
Gate Resistance	R_{g}		0.2	0.85	1.4	Ω	
Turn-On Delay Time	t _{d(on)}			12	18		
Rise Time	t _r	V_{DD} = 75 V, R_L = 15 Ω		7	11		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, $V_{GEN}=10$ V, $R_g=6$ Ω		22	33	ns	
Fall Time	t _f			10	15		
Source-Drain Reverse Recovery Time	t _{rr}	$I_F = 2.8 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		40	70		

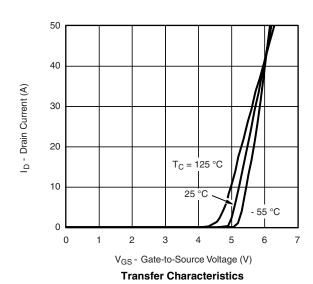
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



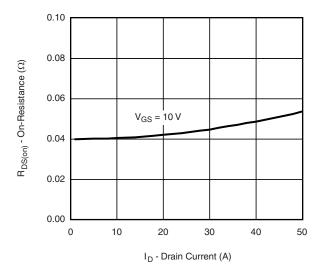




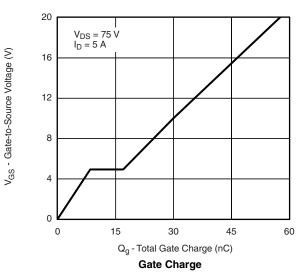


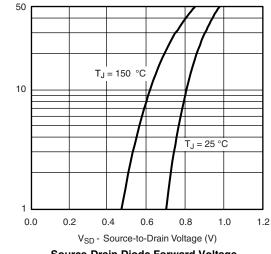


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

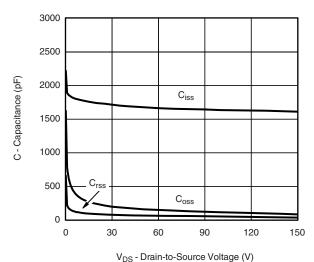


On-Resistance vs. Drain Current

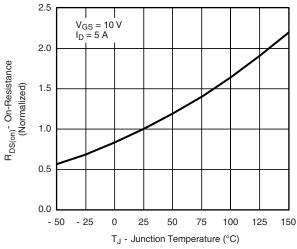




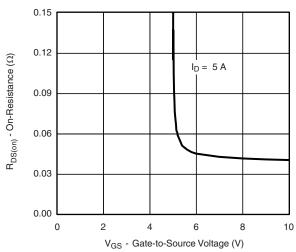
Source-Drain Diode Forward Voltage







On-Resistance vs. Junction Temperature



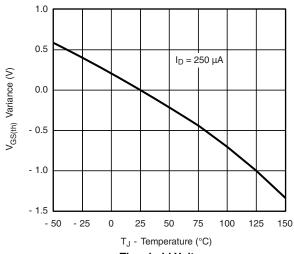
On-Resistance vs. Gate-to-Source Voltage

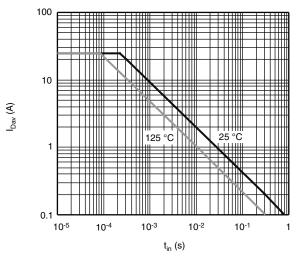
Is - Source Current (A)

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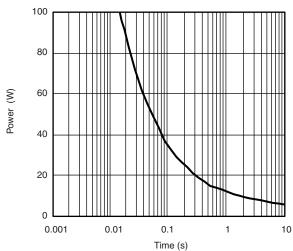
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



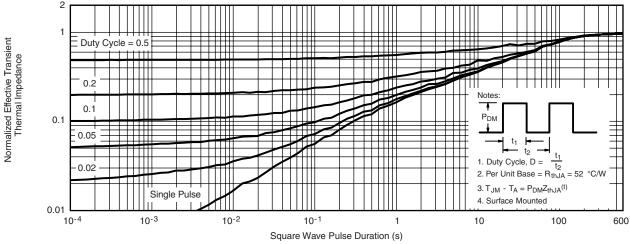


Threshold Voltage

Avalanche Current vs. Time

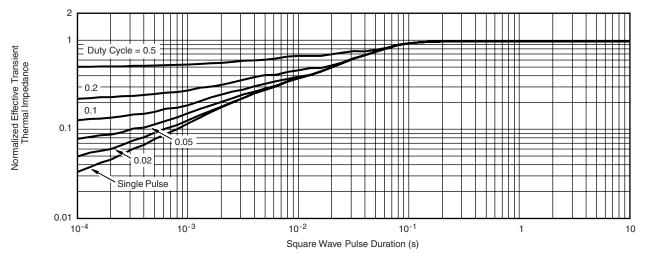


Single Pulse Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

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